· φ	ω	7	on .	CΠ	4	ω	N	L Number
10	172	11	156	44	N	0	Ν	Hits 2
silicon same carbide same key same infiltration	silicon same carbide same key	(silicon same molten same cvd) and infiltration	silicon same molten same cvd	silicon same infiltration same molten same cvd	silicon same molton same cvd	silicon same infiltration same molton same cvd	gb-2022490-\$.did.	Search Text ("4526649").PN.
DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO;	DB USPAT; US-PGPUB; EPO; JPO;
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		47					284					2292					18	Hits
and (key or keyed or keying)	(infiltrate or infiltrant or infiltrating or infiltration or infiltrated))	((silicon adj carbide and (join or joined or joining) and adhesive) and				(infiltrate or infiltrant or infiltrating or infiltration or infiltrated)	(silicon adj carbide and (join or joined or joining) and adhesive) and					silicon adj carbide and (join or joined or joining) and adhesive			US-5526867-\$.DID. OR US-5585190-\$.DID. OR US-6162019-\$.DID.	US-4608318-\$.DID. OR US-4621001-\$.DID. OR US-4921554-\$.DID. OR	US-4070197-\$.DID. OR US-4238540-\$.DID. OR US-4592268-\$.DID. OR	Search Text
EPO; JPO; DERWENT; IBM TDB	US-PGPUB;	USPĀT;	IBM TDB	DERWENT;	EPO; JPO;	US-PGPUB;	USPAT;	IBM TDB	DERWENT;	EPO; JPO;	US-PGPUB;	USPAT;	IBM TDB	DERWENT;	EPO; JPO;	US-PGPUB;	USPAT;	DB
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